

## MODEL **1063**

# WaferMill<sup>™</sup> ion beam delayering solution

Delayer multiple pre-selected regions on a full wafer from the top down. The fully automated process supports all phases of semiconductor processing for CD-SEM sample preparation.

Model 1063 Water/	Mill <sup>™</sup> ion beam delayering solution specifications
Applications	Near-line and in-line
Equipment front- end module (EFEM)	<ul> <li>Manufactured by Brooks Automation; comprises the following:</li> <li>300 mm front-opening unified pod (FOUP) loading station that holds up to 25 wafers</li> <li>Four-axis wafer handling robot with a passive end effector</li> <li>Pre-aligner that orients the wafer notch based on CD-SEM requirements</li> <li>Controller unit</li> </ul>
Pre-pump chamber	300 mm VAT valve interface between the EFEM and load lock
UV light	Dual wave-length ultraviolet (UV) light (253.7 nm and 184.9 nm) mounted within the pre-pump chamber
Load lock	A 300 mm VAT valve interface between the pre-pump chamber and the process chamber; wafer presence sensors indicate when a wafer is in the load lock
Vacuum system	Two dedicated turbomolecular pumps; one in pre-pump chamber and one in process chamber
	Oil-free diaphragm pump to back turbomolecular pumps
	Pressure monitoring with vacuum gauges
Pneumatic supply	Load lock and milling chamber:
	<ul> <li>Process gas: Inert gas (argon) with purity of 99.999% (ultra-high purity); 20 to 30 psi</li> </ul>
	<ul> <li>Control gas: Dry nitrogen; 60 ±5 psi</li> </ul>

Load lock vent gas: Clean, dry air (CDA); 20 to 30 psi

Automatic gas control: Three mass flow controllers (one per ion source)

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#### Process chamber

Linear stage moves the wafer in the x and y direction with 5  $\mu$ m accuracy

Electrostatic chuck: Grips the wafer in place to provide a uniform milling plane by eliminating wafer bow

Wafer presence sensors: Indicate when a wafer is in the process chamber

Integrated wafer mapping based on KLARF files

Ion source assembly: Three ion sources, located 120° apart, at 22.5° from the horizontal plane.

- Variable energy (4.0 to 10.0 keV) operation
- Beam current density: 10 mA/cm<sup>2</sup>
- Beam size: 2 mm
- Point targeting provides the ability to drive the wafer to any point for processing

Turret/rocking assembly:

- Can be rocked ± 175°
- Angular deviation is ± 5° with a variable step size range of 0.1 to 2°
- Rocking speed is 1 rpm.

### Automatic termination

- By timer
- By image processing; milling stops when a specified diameter is reached

#### **User interface**

PC-based interface:

- Accessible from EFEM and chamber side
- Used to control the milling process

Operation indicator: Stack light

#### **Optical system**

Optical system for beam process monitoring and image acquisition:

- Field of view:
  - 15 mm (low magnification)
  - 1.4 mm (high magnification)
- Motorized zoom
- Motorized focus

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## EFEM electrical requirements

- Electrical system: 200-240 VAC, 50/60 Hz, single phase (L1, L2, PE)
- System full load current: 20 A
- Constant load range 5-14 A, depending on configuration
- Overvoltage category II
- Jet power distribution unit is supplied with 10,000 AIC circuit breakers; SCCR 10,000 A
- House vacuum: < 40 kPa (7 psi)</li>
- Vacuum port: 8 mm quick connect

Power	208-240 VAC 50/60 Hz, 5200 Watts
Warranty	One year

